Typical applications
- SMPS, converter
- Electronic ballasts
- Compact fluorescent lamps (CFL)
- Ignition

Climatic
- Max. operating temperature: 125 °C
- Climatic category (IEC 60068-1:2013): 55/125/56

Features
- Special dimensions available on request
- High pulse strength
- Small dimensions
- RoHS-compatible

Construction
- Dielectric: polyethylene terephthalate (polyester, PET)
- Stacked-film technology
- Uncoated

Terminals
- Parallel wire leads, lead-free tinned
- Special lead lengths available on request

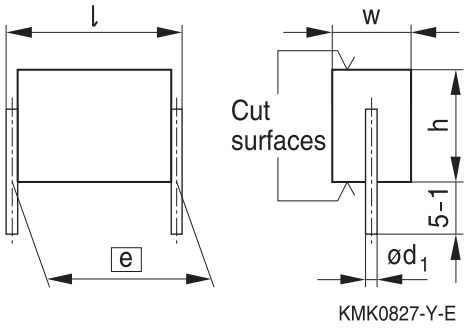
Marking
Rated capacitance (coded),
rated DC voltage

Delivery mode
Bulk (untaped)
Taped (Ammo pack or reel) for lead spacing ≤15.0 mm.
For notes on taping, refer to chapter "Taping and packing".

Notes on mounting
When mounting these capacitors, take into account creepage distances and clearances to adjacent live parts. The insulating strength of the cut surfaces to other live parts of the circuit is 1.5 times the capacitors rated DC voltage, but is always at least 300 V DC.

Capacitors with 7.5 mm lead spacing are only suitable for use with single-clad printed circuit boards.

Dimensional drawing



Dimensions in mm

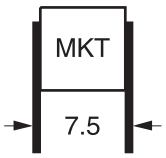
Lead spacing e ±0.4	Lead diameter d_1 ±0.05	Type
7.5	0.5	B32560
15.0	0.6	B32562J
	0.8	B32562H
22.5	0.8	B32563
27.5	0.8	B32564

Overview of available types

Lead spacing	7.5 mm					15.0 mm				22.5 mm		
Type	B32560					B32562				B32563		
Page	5					7				8		
V_R (V DC)	63	100	250	400	630	100	250	400	630	100	250	400
V_{RMS} (V AC)	40	63	160	200	400	63	160	200	350	63	160	200
C_R (µF)												
0.0010					■							
0.0015					■							
0.0022					■							
0.0033					■							
0.0047					■							
0.0068				■	■							
0.010				■	■							
0.015				■	■							
0.022				■	■							
0.033				■								
0.047			■	■								
0.068			■	■								
0.10			■	■								
0.15			■	■								
0.22		■	■	■				■	■			
0.33		■	■					■	■			
0.47		■	■				■	■	■			
0.68		■	■				■	■				
1.0	■	■					■	■				■
1.5	■	■					■	■				■
2.2	■	■				■	■				■	■
3.3	■	■				■	■				■	
4.7	■					■					■	
6.8						■				■		
10						■				■		
15										■		
22										■		

Overview of available types

Lead spacing	27.5 mm			
Type	B32564			
Page	9			
V_R (V DC)	100	250	400	420
V_{RMS} (V AC)	63	160	200	200
C_R (µF)				
1.5				
2.2				
3.3				
4.7				
6.8				
10				
15				
22				
33				



Ordering codes and packing units (lead spacing 7.5 mm)

V_R V DC	V_{RMS} f ≤60 Hz V AC	C_R µF	Max. dimensions w × h × l mm	Ordering code (composition see below)	Ammo pack pcs./MOQ	Reel pcs./MOQ	Untaped pcs./MOQ
63	40	1.0	4.0 × 6.8 × 9.0	B32560J0105+***	8800	7200	4000
		1.5	5.1 × 7.6 × 9.0	B32560J0155+***	6800	5600	2000
		2.2	6.5 × 8.2 × 9.0	B32560J0225+***	6000	4800	2000
		3.3	8.5 × 9.1 × 9.0	B32560J0335+000	–	–	1400
		4.7	9.8 × 11.0 × 9.0	B32560J0475+000	–	–	1000
100	63	0.22	2.5 × 5.1 × 9.0	B32560J1224+***	12400	10000	7600
		0.33	2.7 × 5.7 × 9.0	B32560J1334+***	12000	9600	6000
		0.47	3.4 × 6.1 × 9.0	B32560J1474+***	9600	8000	4800
		0.68	4.2 × 6.5 × 9.0	B32560J1684+***	8000	6400	3600
		1.0	5.5 × 7.0 × 9.0	B32560J1105+***	6000	4800	2000
		1.5	6.7 × 8.2 × 9.0	B32560J1155+***	5000	4000	1600
		2.2	8.5 × 9.2 × 9.0	B32560J1225+000	–	–	1200
		3.3	9.5 × 11.0 × 9.0	B32560J1335+000	–	–	800
250	160	0.047	2.5 × 5.2 × 9.0	B32560J3473+***	13000	10400	7600
		0.068	2.6 × 5.7 × 9.0	B32560J3683+***	12400	10000	6800
		0.10	3.2 × 6.1 × 9.0	B32560J3104+***	12400	8000	4800
		0.15	3.9 × 7.0 × 9.0	B32560J3154+***	8200	6800	3600
		0.22	4.9 × 7.5 × 9.0	B32560J3224+***	6800	5200	2600
		0.33	6.4 × 8.2 × 9.0	B32560J3334+***	5200	4400	1800
		0.47	7.4 × 9.8 × 9.0	B32560J3474+000	–	–	1200
		0.68	9.5 × 11.0 × 9.0	B32560J3684+000	–	–	800

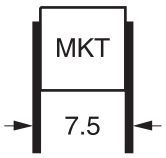
MOQ = Minimum Order Quantity, consisting of 4 packing units.
Further E series and intermediate capacitance values on request.

Special dimensions available on request.
For corresponding design rules, refer to chapter "General technical information", section 1.3.2.

Composition of ordering code

+ = Capacitance tolerance code:
- M = ±20%
- K = ±10%
- J = ±5%

*** = Packaging code:
- 289 = Ammo pack
- 189 = Reel
- 000 = Untaped (lead length 5 −1 mm)



B32560

General purpose (stacked) SilverCap™

Ordering codes and packing units (lead spacing 7.5 mm)

V_R V DC	V_{RMS} f ≤60 Hz V AC	C_R µF	Max. dimensions w × h × l mm	Ordering code (composition see below)	Ammo pack pcs./MOQ	Reel pcs./MOQ	Untaped pcs./MOQ
400	200	0.0068	2.5 × 5.5 × 9.0	B32560J6682+***	14000	11200	7600
		0.010	2.5 × 5.5 × 9.0	B32560J6103+***	12800	10400	7200
		0.015	2.5 × 5.5 × 9.0	B32560J6153+***	13000	10400	7200
		0.022	2.5 × 5.5 × 9.0	B32560J6223+***	12400	10000	6800
		0.033	2.6 × 6.0 × 9.0	B32560J6333+***	12400	10000	6400
		0.047	3.2 × 6.5 × 9.0	B32560J6473+***	10400	8400	4800
		0.068	3.8 × 7.3 × 9.0	B32560J6683+***	8600	7200	3600
		0.10	4.9 × 7.7 × 9.0	B32560J6104+***	6800	5600	2000
		0.15	6.5 × 8.2 × 9.0	B32560J6154+***	5400	4000	1800
		0.22	7.7 × 9.8 × 9.0	B32560J6224+000	–	–	1200
630	400	0.0010	2.5 × 5.5 × 9.0	B32560J8102+***	14800	12000	9200
		0.0015	2.5 × 5.5 × 9.0	B32560J8152+***	13000	2600	7200
		0.0022	2.5 × 5.5 × 9.0	B32560J8222+***	13400	10800	7200
		0.0033	2.5 × 5.5 × 9.0	B32560J8332+***	14000	11200	7600
		0.0047	2.5 × 5.5 × 9.0	B32560J8472+***	13600	10800	7200
		0.0068	3.2 × 6.5 × 9.0	B32560J8682+***	15000	9200	5200
		0.010	3.8 × 7.5 × 9.0	B32560J8103+***	9000	9200	4000
		0.015	4.6 × 8.3 × 9.0	B32560J8153+000	–	–	2400
		0.022	5.7 × 8.6 × 9.0	B32560J8223+000	–	–	1600

MOQ = Minimum Order Quantity, consisting of 4 packing units.
Further E series and intermediate capacitance values on request.

Special dimensions available on request.
For corresponding design rules, refer to chapter "General technical information", section 1.3.2.

Composition of ordering code

+ = Capacitance tolerance code:
- M = ±20%
- K = ±10%
- J = ±5%

*** = Packaging code:
- 289 = Ammo pack
- 189 = Reel
- 000 = Untaped (lead length 5 −1 mm)

Ordering codes and packing units (lead spacing 15 mm)

V_R V DC	V_{RMS} f ≤60 Hz V AC	C_R µF	Max. dimensions w × h × l mm	Ordering code (composition see below)	Ammo pack pcs./MOQ	Reel pcs./ MOQ	Untaped pcs./ MOQ
100	63	2.2	4.9 × 8.0 × 16.5	B32562J1225+***	4760	5200	3200
		3.3	6.0 × 9.3 × 16.5	B32562J1335+***	3840	4000	2000
		4.7	7.3 × 10.6 × 16.5	B32562H1475+***	3160	3600	1600
		6.8	9.0 × 11.8 × 16.5	B32562H1685+***	2560	2800	1160
		10	11.8 × 13.0 × 16.5	B32562H1106+000	–	–	800
250	160	0.47	5.0 × 6.7 × 16.5	B32562J3474+***	4760	5200	3800
		0.68	6.0 × 7.8 × 16.5	B32562J3684+***	3840	4000	2000
		1.0	7.0 × 9.3 × 16.5	B32562J3105+***	3320	3600	2000
		1.5	8.7 × 11.0 × 16.5	B32562H3155+***	2640	2800	1200
		2.2	10.7 × 12.8 × 16.5	B32562H3225+000	–	–	800
		3.3	13.9 × 14.5 × 16.5	B32562H3335+000	–	–	600
400	200	0.22	4.7 × 7.5 × 16.5	B32562J6224+***	4960	5200	3400
		0.33	6.0 × 8.3 × 16.5	B32562J6334+***	3840	4000	2000
		0.47	7.3 × 9.3 × 16.5	B32562J6474+***	3160	3600	1800
		0.68	8.9 × 10.8 × 16.5	B32562H6684+***	2560	2800	1200
		1.0	10.9 × 12.5 × 16.5	B32562H6105+000	–	–	800
		1.5	13.7 × 15.2 × 16.5	B32562H6155+000	–	–	400
630	350	0.22	9.2 × 12.2 × 16.5	B32562H8224+000	–	–	1400
		0.33	11.2 × 14.2 × 16.5	B32562H8334+000	–	–	1000
		0.47	13.5 × 16.3 × 16.5	B32562H8474+000	–	–	720

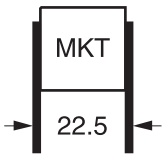
MOQ = Minimum Order Quantity, consisting of 4 packing units.
Further E series and intermediate capacitance values on request.

Special dimensions available on request.
For corresponding design rules, refer to chapter "General technical information", section 1.3.2.

Composition of ordering code

+ = Capacitance tolerance code:
- M = ±20%
- K = ±10%
- J = ±5%

*** = Packaging code:
- 289 = Ammo pack
- 189 = Reel
- 000 = Untaped (lead length 5 −1 mm)



B32563

General purpose (stacked) SilverCap™

Ordering codes and packing units (lead spacing 22.5 mm)

V_R V DC	V_{RMS} f ≤60 Hz V AC	C_R µF	Max. dimensions w × h × l mm	Ordering code (composition see below)	Untaped pcs./MOQ
100	63	6.8	7.0 × 10.5 × 24.0	B32563J1685+000	3680
		10	8.6 × 12.2 × 24.0	B32563J1106+000	3840
		15	10.9 × 14.0 × 24.0	B32563J1156+000	2480
		22	12.8 × 17.2 × 24.0	B32563J1226+000	1440
250	160	2.2	8.3 × 11.2 × 24.0	B32563J3225+000	2960
		3.3	10.1 × 13.5 × 24.0	B32563J3335+000	2800
		4.7	12.2 × 15.5 × 24.0	B32563J3475+000	1560
400	200	1.0	8.3 × 11.2 × 24.0	B32563J6105+000	3400
		1.5	10.3 × 13.2 × 24.0	B32563J6155+000	2640
		2.2	12.6 × 15.5 × 24.0	B32563J6225+000	1440

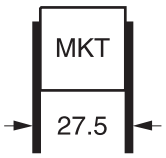
MOQ = Minimum Order Quantity, consisting of 4 packing units.
Further E series and intermediate capacitance values on request.

Special dimensions available on request.
For corresponding design rules, refer to chapter "General technical information", section 1.3.2.

Composition of ordering code

+ = Capacitance tolerance code:
M = ±20%
K = ±10%
J = ±5%

Packaging code:
000 = Untaped (lead length 5 − 1 mm)



Ordering codes and packing units (lead spacing 27.5 mm)

V_R V DC	V_{RMS} f ≤60 Hz V AC	C_R µF	Max. dimensions w × h × l mm	Ordering code (composition see below)	Untaped pcs./MOQ
100	63	10	7.6 × 11.0 × 29.0	B32564J1106+000	2720
		15	9.1 × 13.5 × 29.0	B32564J1156+000	1720
		22	11.0 × 16.0 × 29.0	B32564J1226+000	1280
		33	13.0 × 19.8 × 29.0	B32564J1336+000	1440
250	160	3.3	7.9 × 14.0 × 29.0	B32564J3335+000	3000
		4.7	9.6 × 15.8 × 29.0	B32564J3475+000	1600
		6.8	11.9 × 18.0 × 29.0	B32564J3685+000	1200
		10	13.8 × 22.5 × 29.0	B32564J3106+000	1120
400	200	1.5	7.8 × 14.2 × 29.0	B32564J6155+000	3000
		2.2	9.6 × 16.4 × 29.0	B32564J6225+000	1600
		3.3	12.2 × 18.8 × 29.0	B32564J6335+000	1320
		4.7	14.2 × 22.8 × 29.0	B32564J6475+000	1040
420	200	4.7	16.0 × 20.0 × 29.0	B32564T6475K000	1160
		6.8	16.0 × 20.0 × 29.0	B32564T6685K000	1160

MOQ = Minimum Order Quantity, consisting of 4 packing units.
Further E series and intermediate capacitance values on request.

Special dimensions available on request.
For corresponding design rules, refer to chapter "General technical information", section 1.3.2.
The technical data given on page 10 do not apply to 420 V series. Please contact your nearest TDK representative if you need further information.

Composition of ordering code

+ = Capacitance tolerance code:
M = ±20%
K = ±10%
J = ±5%

Packaging code:
000 = Untaped (lead length 5 − 1 mm)

Technical data

Reference standard: IEC 60384-2:2005. All data given at T = 20 ºC, unless otherwise specified.

Operating temperature range	Max. operating temperature $T_{op,max}$	+125 °C		
	Upper category temperature T_{max}	+125 °C		
	Lower category temperature T_{min}	−55 °C		
	Rated temperature T_R	+85 °C		
Dissipation factor tan δ (in 10^{-3}) at 20 °C (upper limit values)	at	$C_R \leq 0.1$ µF	0.1 µF < $C_R \leq 1$ µF	$C_R > 1$ µF
	1 kHz	8	8	10
	10 kHz	15	15	–
	100 kHz	30	–	–
Insulation resistance R_{ins} or time constant $\tau = C_R \cdot R_{ins}$ at 20 °C, rel. humidity ≤ 65% (minimum as-delivered values)	V_R	$C_R \leq 0.33$ µF	$C_R > 0.33$ µF	
	≤ 100 V DC	3750 MΩ	1250 s	
	≥ 250 V DC	7500 MΩ	2500 s	
DC test voltage	1.4 · V_R, 2 s			
Category voltage V_C (continuous operation with V_{DC} or V_{AC} at f ≤ 60 Hz)	T_{op} (°C)	DC voltage derating	AC voltage derating	
	$T_{op} \leq 85$	$V_C = V_R$	$V_{C,RMS}=V_{RMS}$	
	$85<T_{op}\leq125$	$V_C = V_R \cdot (165-T_{op})/80$	$V_{C,RMS}=V_{RMS} \cdot (165-T_{op})/80$	
Operating voltage V_{op} for short operating periods (V_{DC} or V_{AC} at f ≤ 60 Hz)	T_{op} (°C)	DC voltage (max. hours)	AC voltage (max. hours)	
	$T_{op} \leq 100$	$V_{op} = 1.25 \cdot V_C$ (2000 h)	$V_{op} = 1.0 \cdot V_{C,RMS}$ (2000 h)	
	$100<T_{op}\leq125$	$V_{op} = 1.25 \cdot V_C$ (1000 h)	$V_{op} = 1.0 \cdot V_{C,RMS}$ (1000 h)	
Reliability:				
Failure rate λ	2 fit (≤ 2 · 10^{-9} /h) at 0.5 · V_R, 40 °C			
Service life t_{SL}	100 000 h at 1.0 · V_R, 85 °C			
	For conversion to other operating conditions and temperatures, refer to chapter "Reliability".			
Failure criteria:				
Total failure	Short circuit or open circuit			
Failure due to variation of parameters	Capacitance change |ΔC/C|	> 10%		
	Dissipation factor tan δ	> 2 · upper limit value		
	Insulation resistance R_{ins}	< 150 MΩ ($C_R \leq 0.33$ µF)		
	or time constant $\tau = C_R \cdot R_{ins}$	< 50 s ($C_R > 0.33$ µF)		

Pulse handling capability

"dV/dt" represents the maximum permissible voltage change per unit of time for non-sinusoidal voltages, expressed in V/µs.

"k_0" represents the maximum permissible pulse characteristic of the waveform applied to the capacitor, expressed in $V^2/\mu s$.

Note:
The values of dV/dt and k_0 provided below must not be exceeded in order to avoid damaging the capacitor. These parameters are given for isolated pulses in such a way that the heat generated by one pulse will be completely dissipated before applying the next pulse. For a train of pulses, please refer to the curves of permissible AC voltage-current versus frequency.

dV/dt values

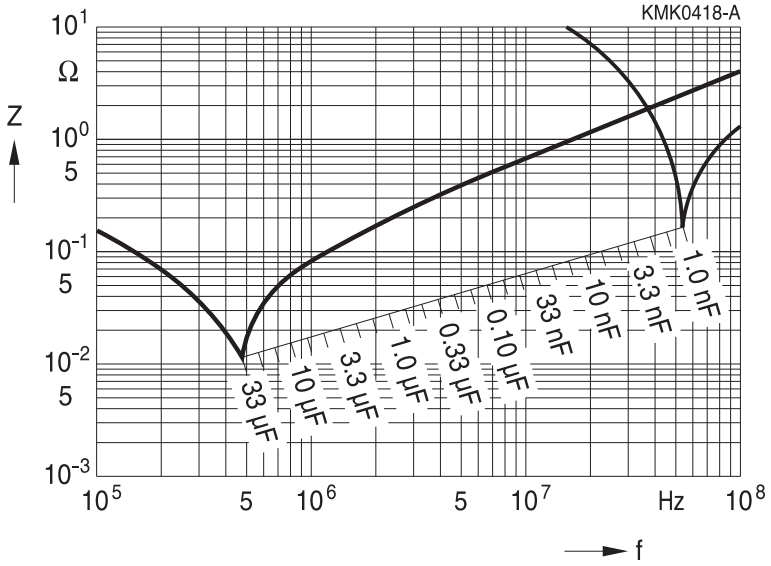
Lead spacing		7.5 mm	15 mm	22.5 mm	27.5 mm
V_R V DC	V_{RMS} V AC	dV/dt in V/µs			
63	40	120	–	–	–
100	63	150	50	50	25
250	160	200	100	100	50
400	200	275	125	125	60
420	200	–	–	–	60
630	350	–	150	–	–
630	400	320	–	–	–

k_0 values

Lead spacing		7.5 mm	15 mm	22.5 mm	27.5 mm
V_R V DC	V_{RMS} V AC	k_0 in $V^2/\mu s$			
63	40	15 000	–	–	–
100	63	30 000	10 000	10 000	5 000
250	160	100 000	50 000	50 000	25 000
400	200	220 000	100 000	100 000	50 000
420	200	–	–	–	50 000
630	350	–	190 000	–	–
630	400	400 000	–	–	–

Impedance Z versus frequency f

(typical values)

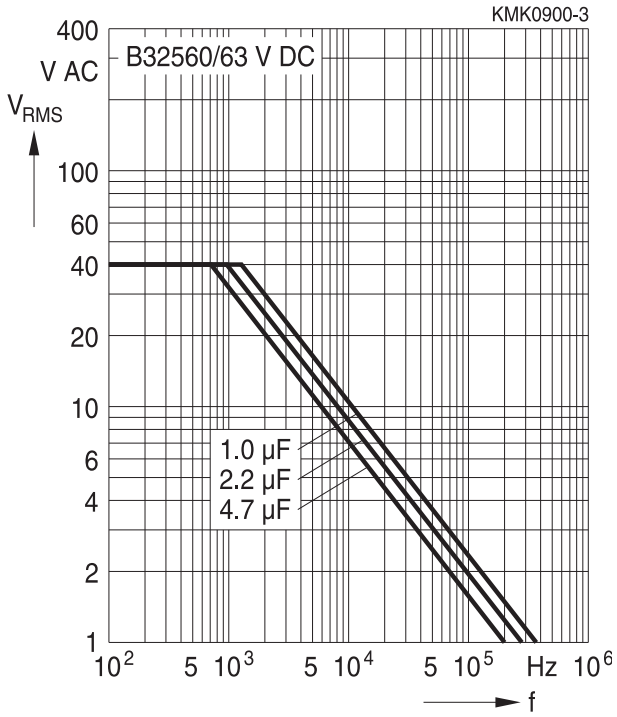


Permissible AC voltage V_{RMS} versus frequency f (for sinusoidal waveforms, $T_A \leq 55$ °C)

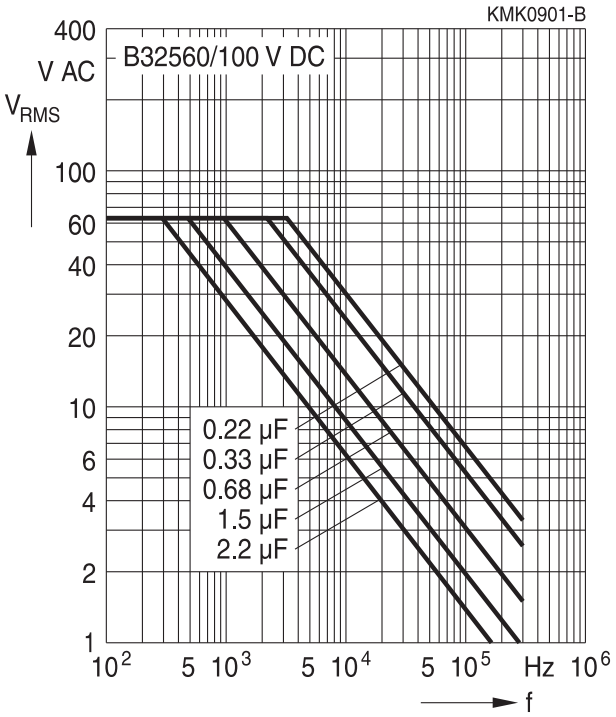
For T_A >55 °C, please refer to "General technical information", section 3.2.3.

Lead spacing 7.5 mm

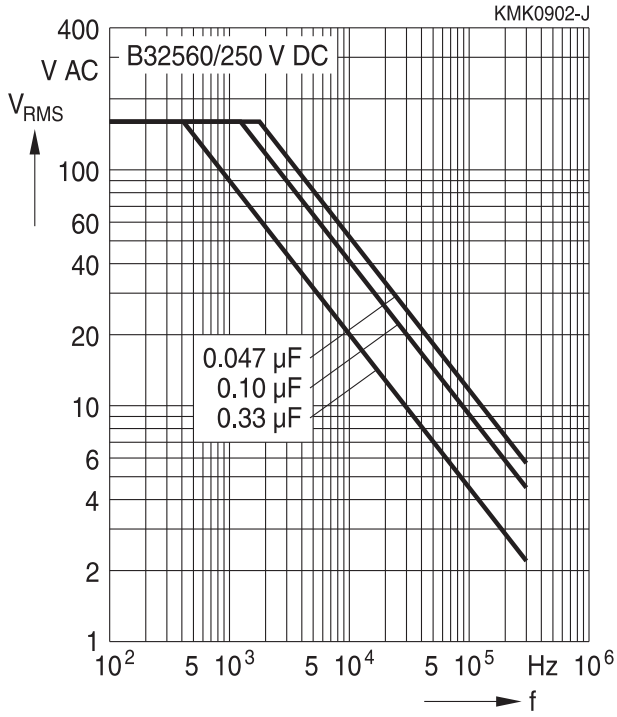
63 V DC/40 V AC



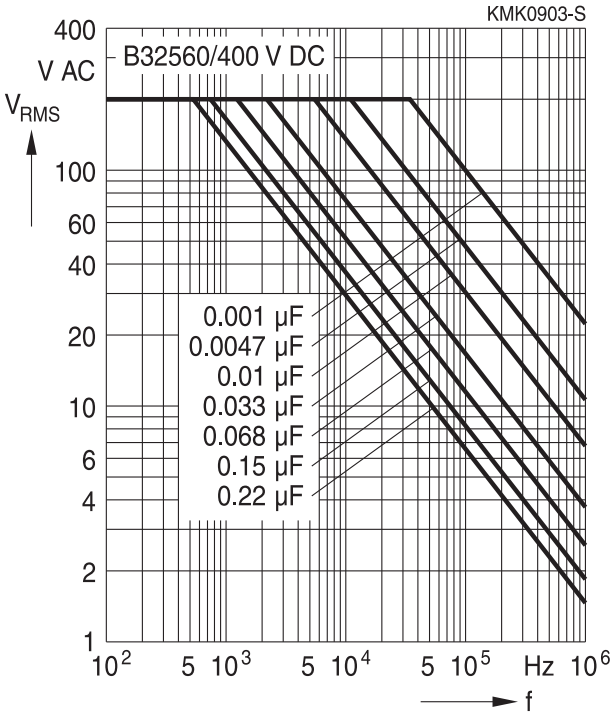
100 V DC/63 V AC

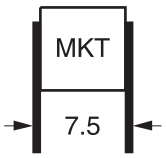


250 V DC/160 V AC



400 V DC/200 V AC



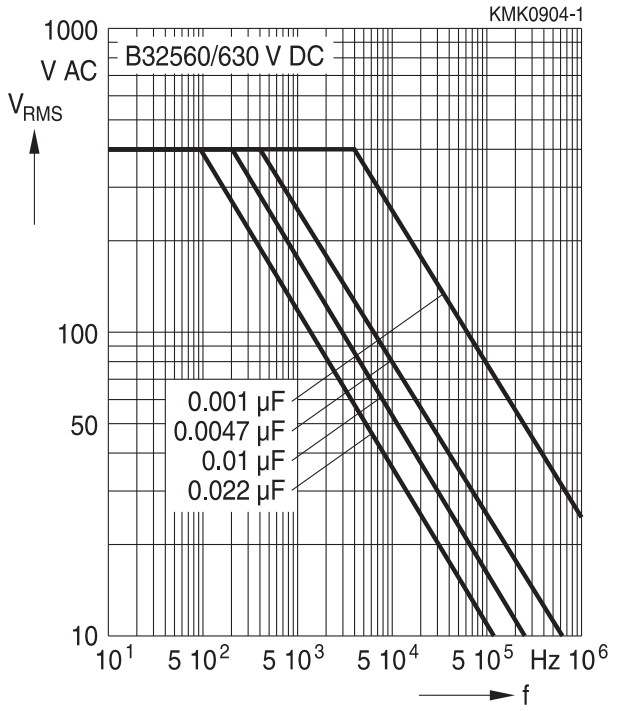


Permissible AC voltage V_{RMS} versus frequency f (for sinusoidal waveforms, $T_A \leq 55$ °C)

For T_A >55 °C, please refer to "General technical information", section 3.2.3.

Lead spacing 7.5 mm

630 V DC/400 V AC

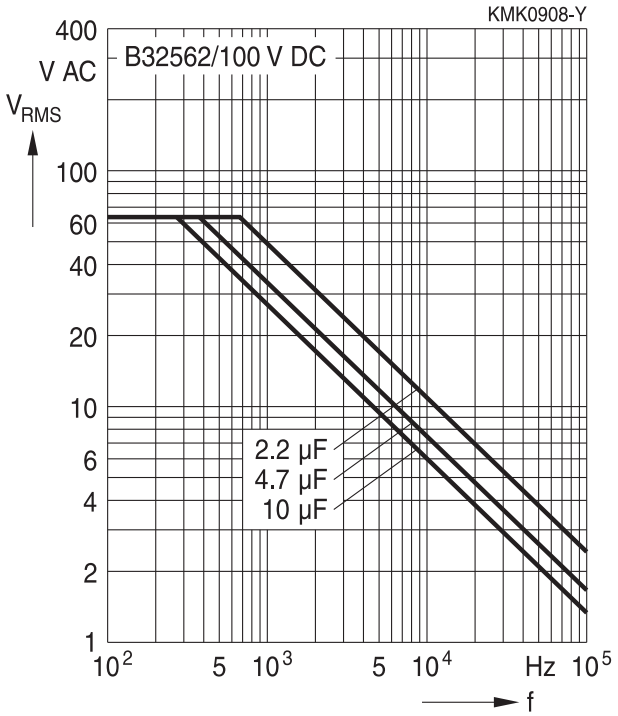


Permissible AC voltage V_{RMS} versus frequency f (for sinusoidal waveforms, $T_A \leq 55$ °C)

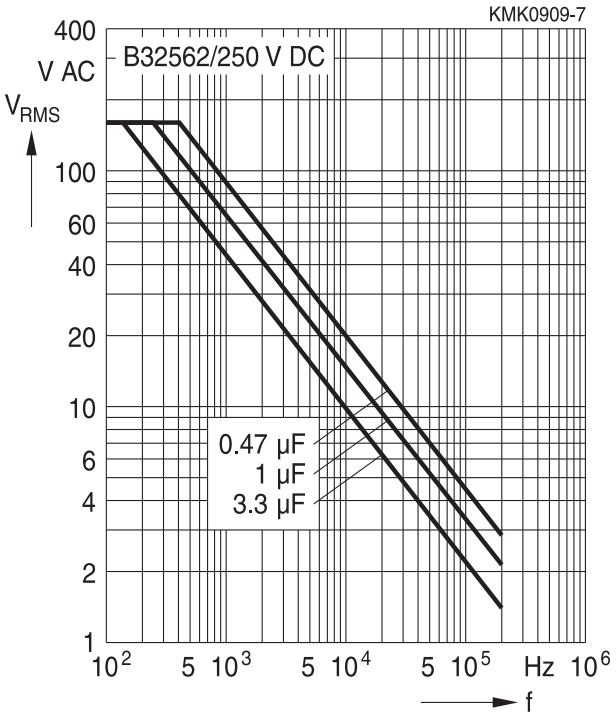
For T_A >55 °C, please refer to "General technical information", section 3.2.3.

Lead spacing 15 mm

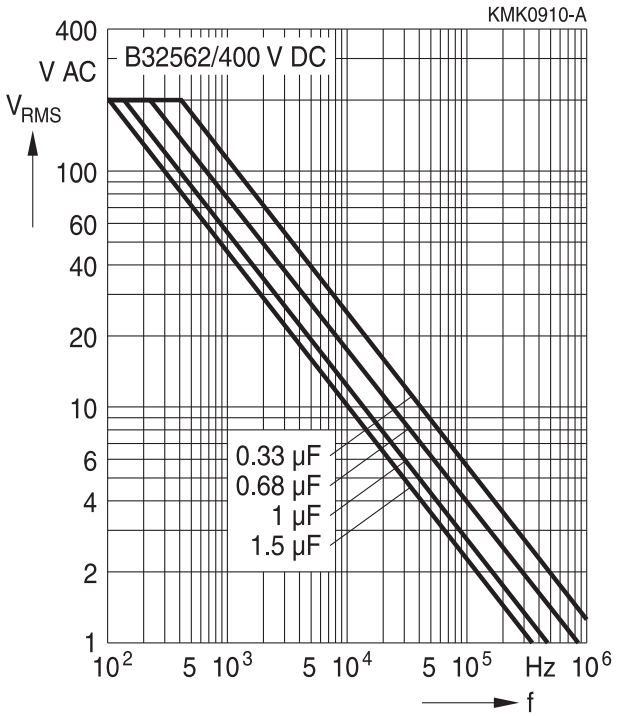
100 V DC/63 V AC



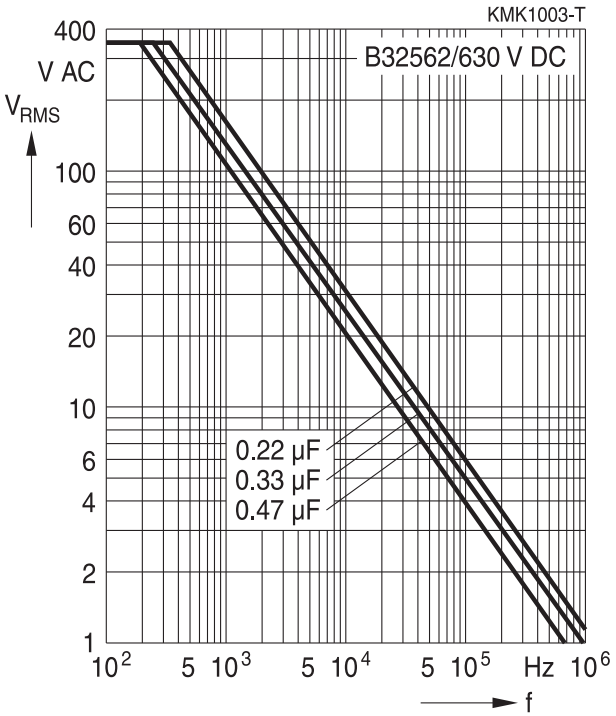
250 V DC/160 V AC

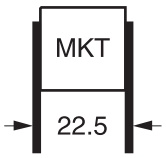


400 V DC/200 V AC



630 V DC/350 V AC



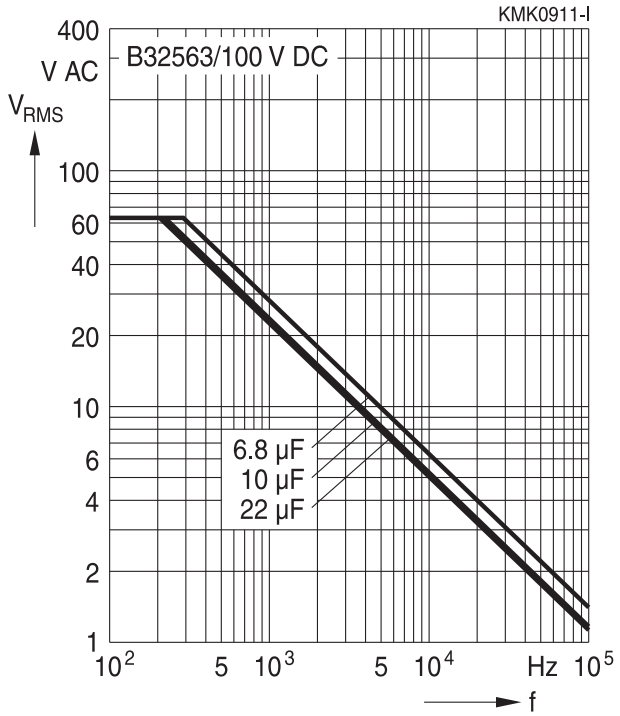


Permissible AC voltage V_{RMS} versus frequency f (for sinusoidal waveforms, $T_A \leq 55$ °C)

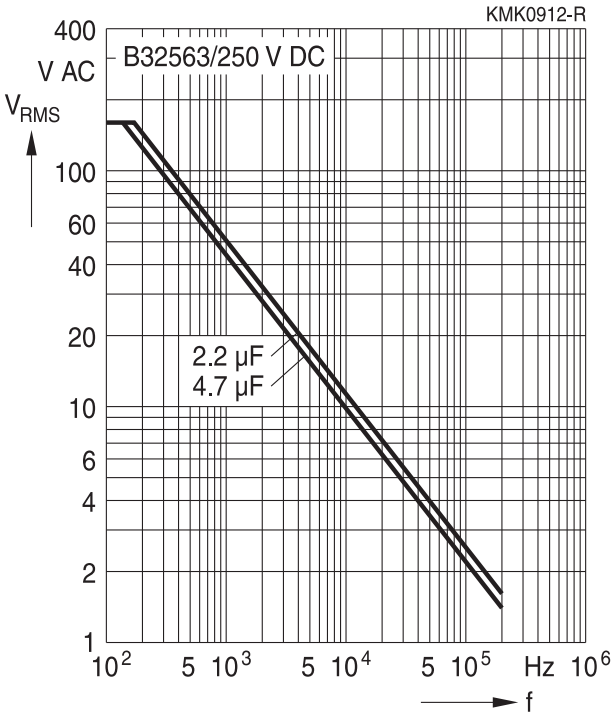
For T_A >55 °C, please refer to "General technical information", section 3.2.3.

Lead spacing 22.5 mm

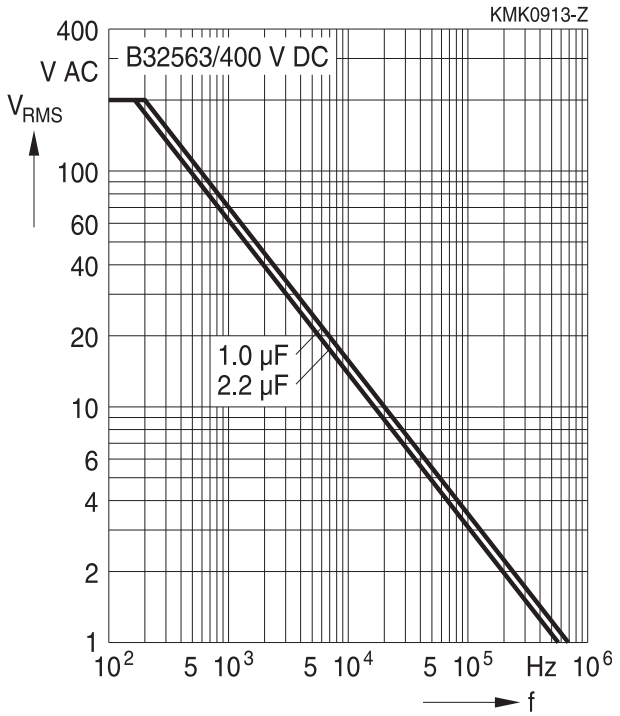
100 V DC/63 V AC



250 V DC/160 V AC



400 V DC/200 V AC

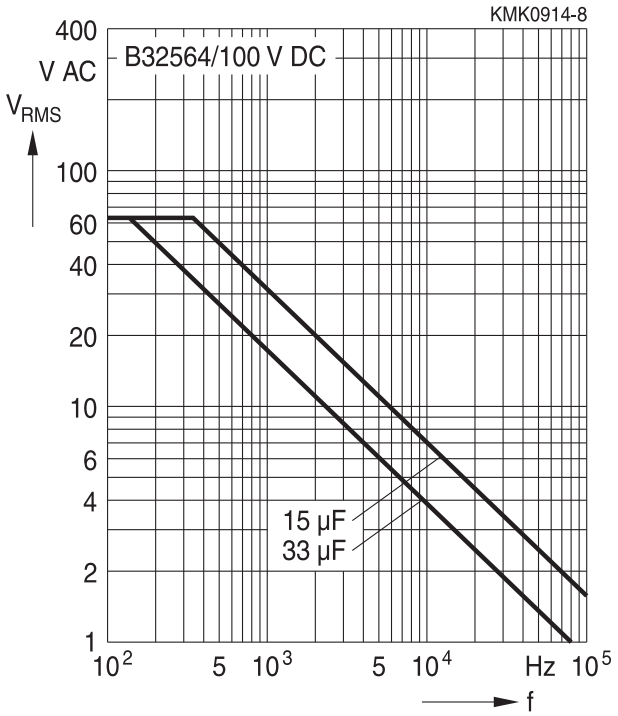


Permissible AC voltage V_{RMS} versus frequency f (for sinusoidal waveforms, $T_A \leq 55$ °C)

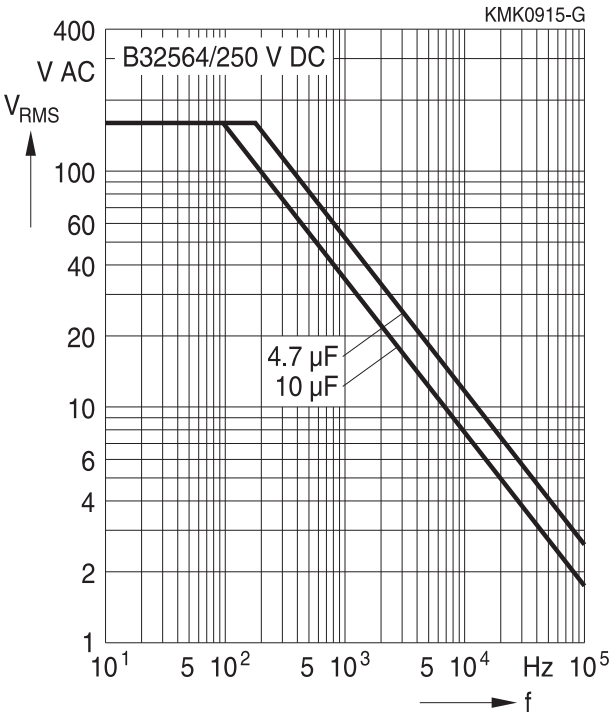
For T_A >55 °C, please refer to "General technical information", section 3.2.3.

Lead spacing 27.5 mm

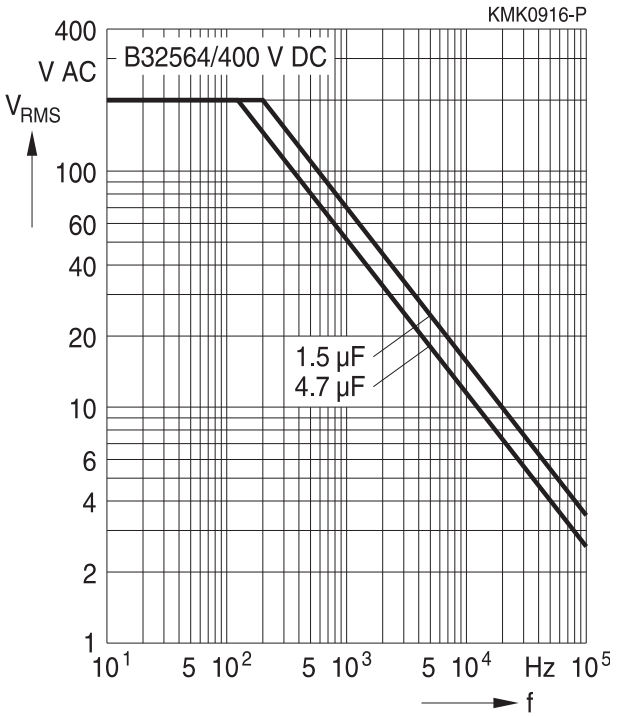
100 V DC/63 V AC



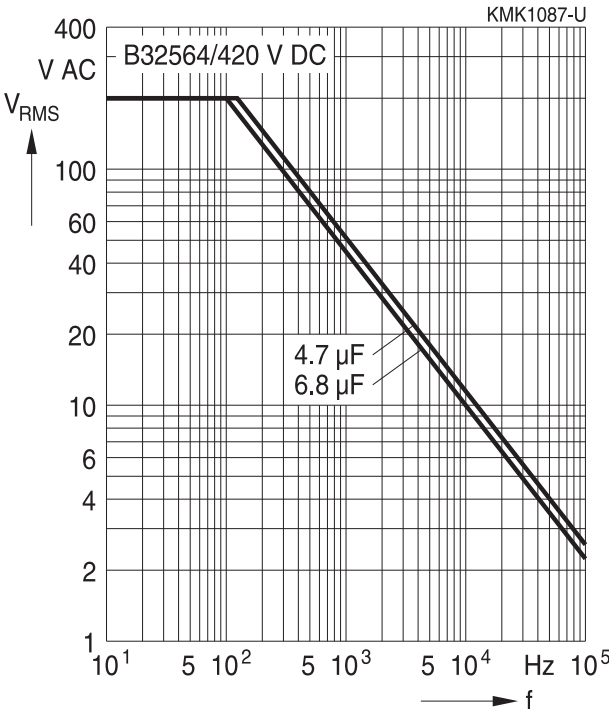
250 V DC/160 V AC



400 V DC/200 V AC



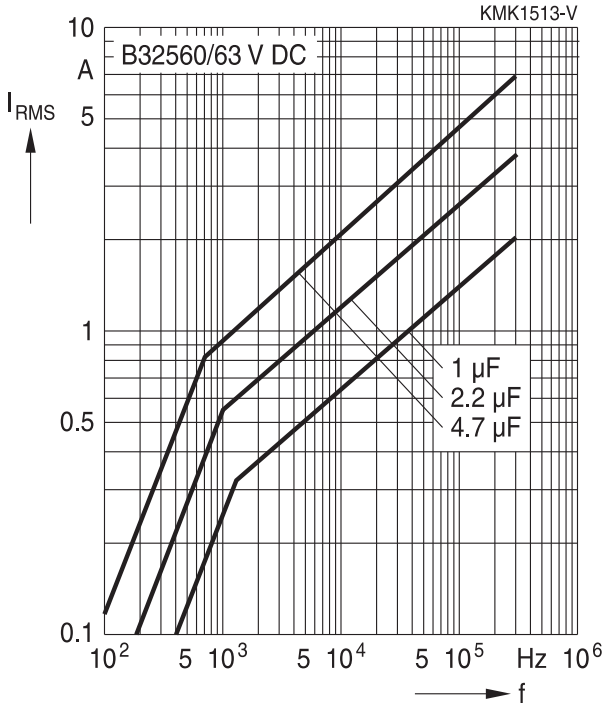
420 V DC/200 V AC



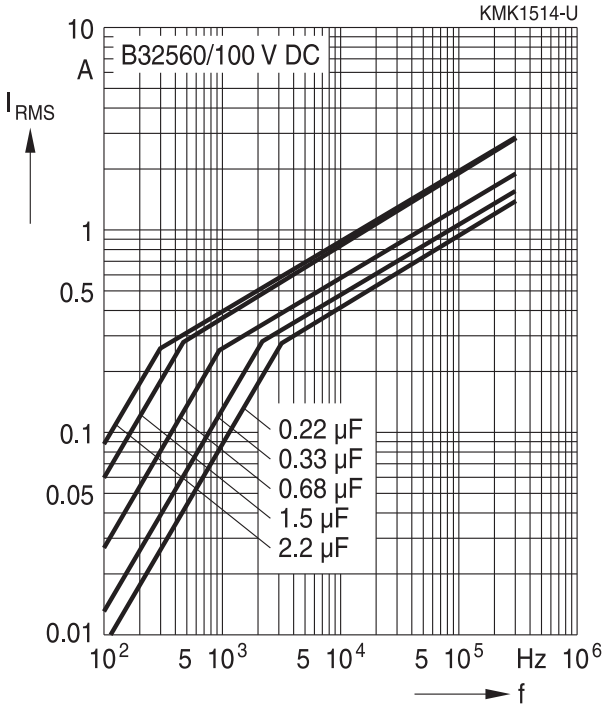
Permissible current I_{RMS} versus frequency f (for sinusoidal waveforms, $T_A \leq 55$ °C)

Lead spacing 7.5 mm

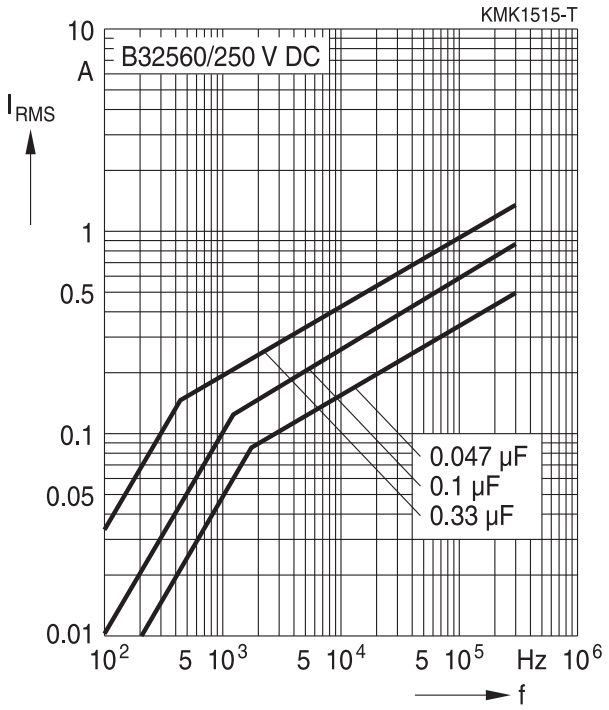
63 V DC/40 V AC



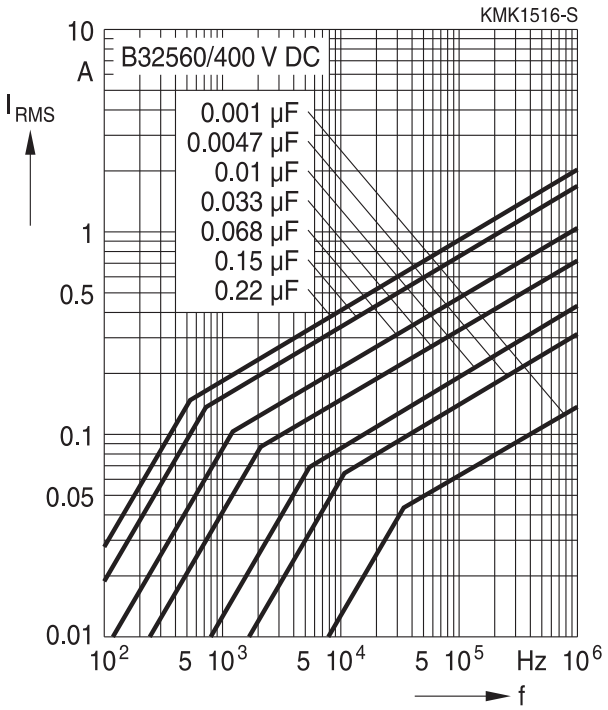
100 V DC/63 V AC

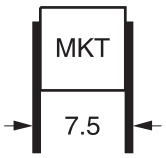


250 V DC/160 V AC



400 V DC/200 V AC

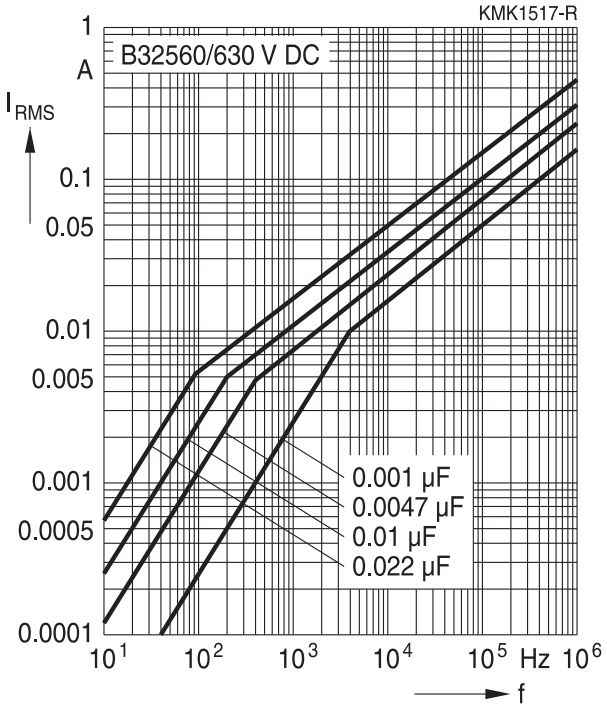




Permissible current I_{RMS} versus frequency f (for sinusoidal waveforms, $T_A \leq 55$ °C)

Lead spacing 7.5 mm

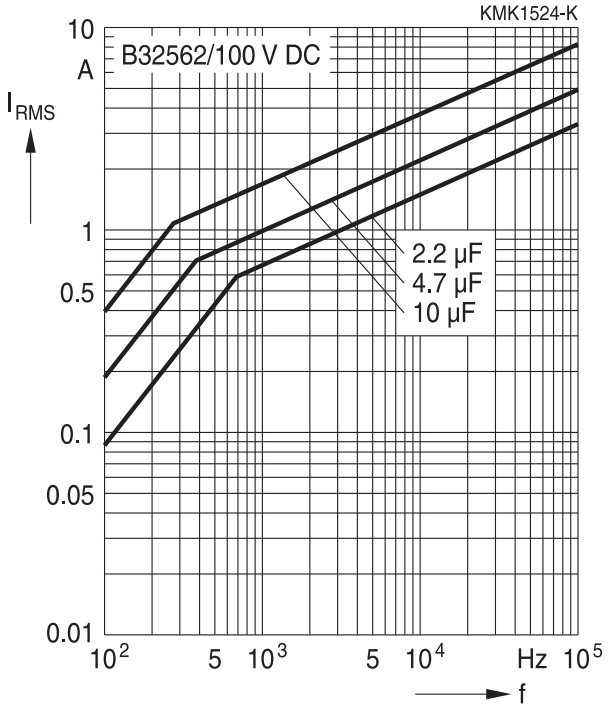
630 V DC/400 V AC



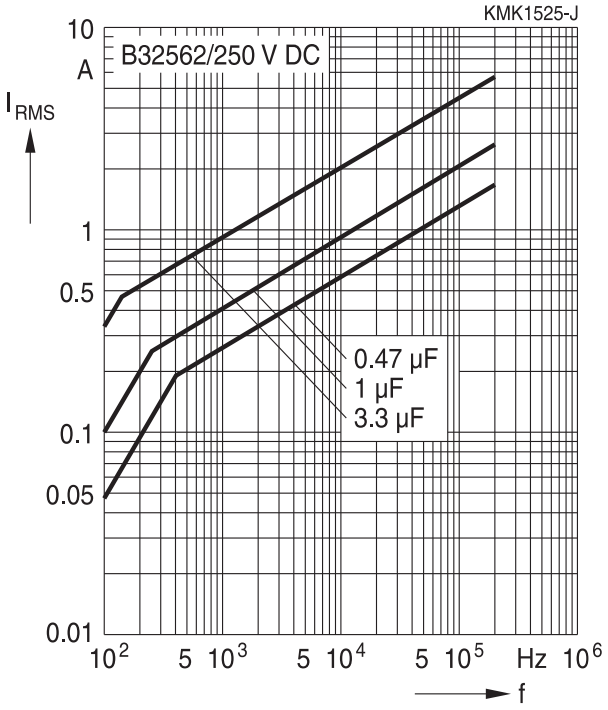
Permissible current I_{RMS} versus frequency f (for sinusoidal waveforms, $T_A \leq 55$ °C)

Lead spacing 15 mm

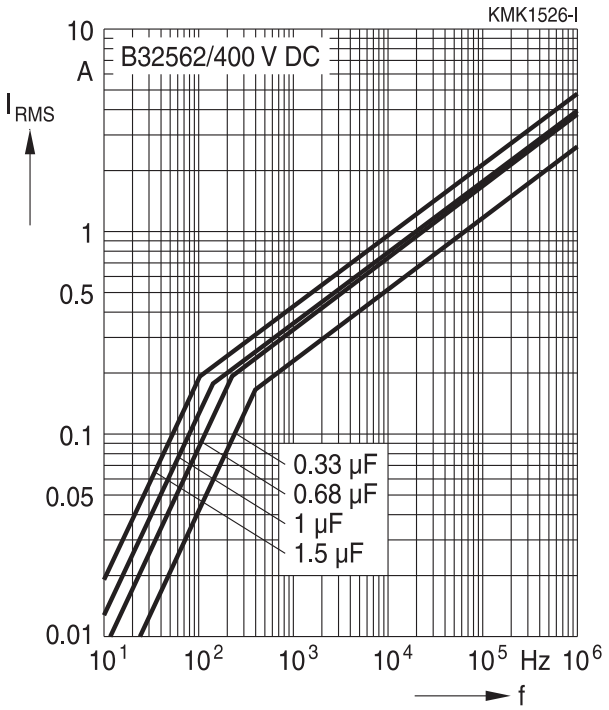
100 V DC/63 V AC



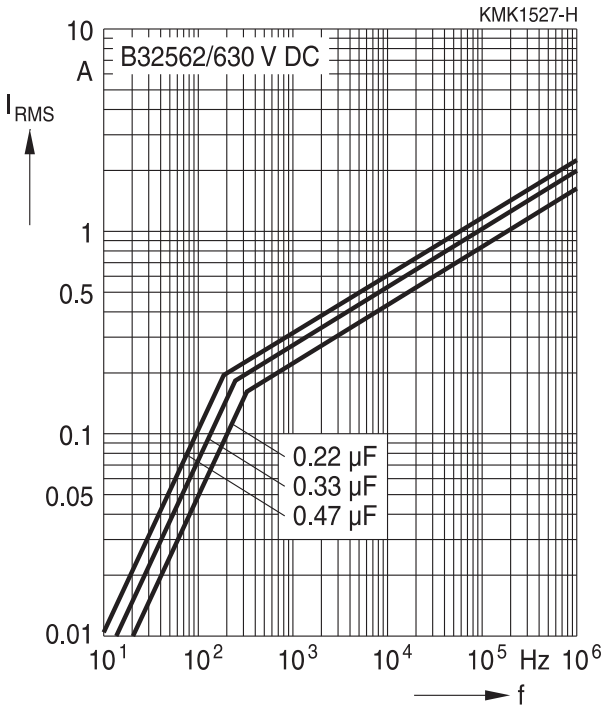
250 V DC/160 V AC



400 V DC/200 V AC



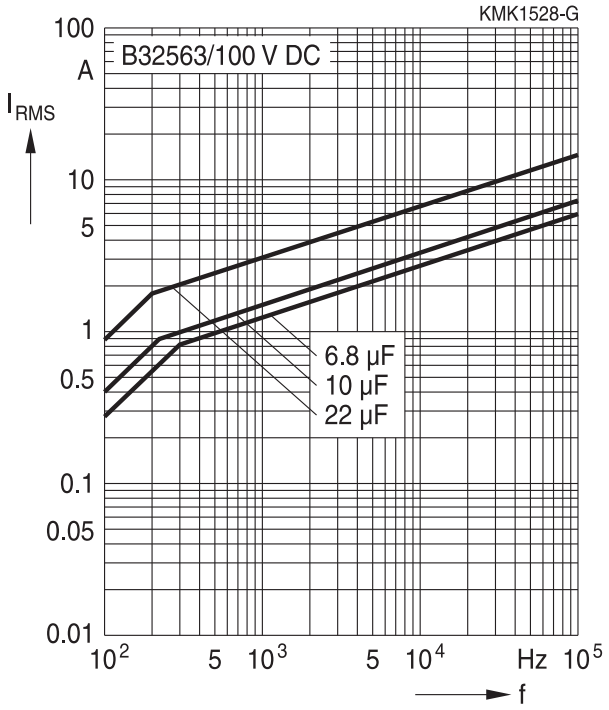
630 V DC/350 V AC



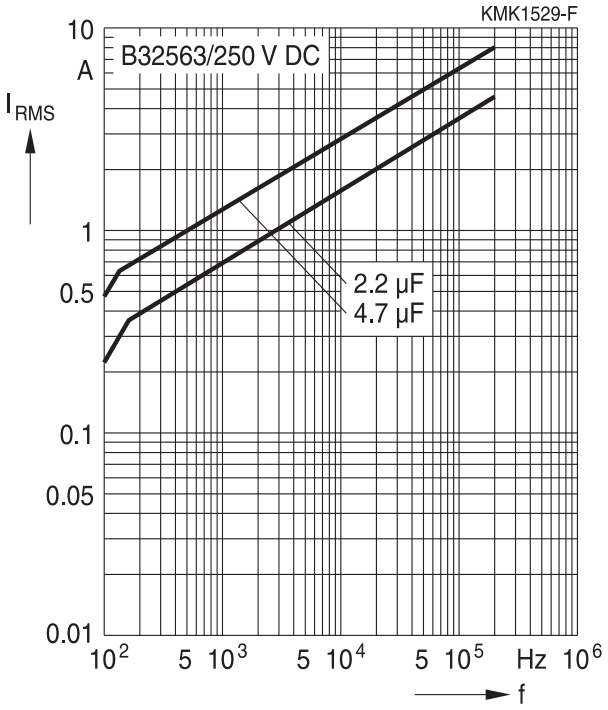
Permissible current I_{RMS} versus frequency f (for sinusoidal waveforms, $T_A \leq 55$ °C)

Lead spacing 22.5 mm

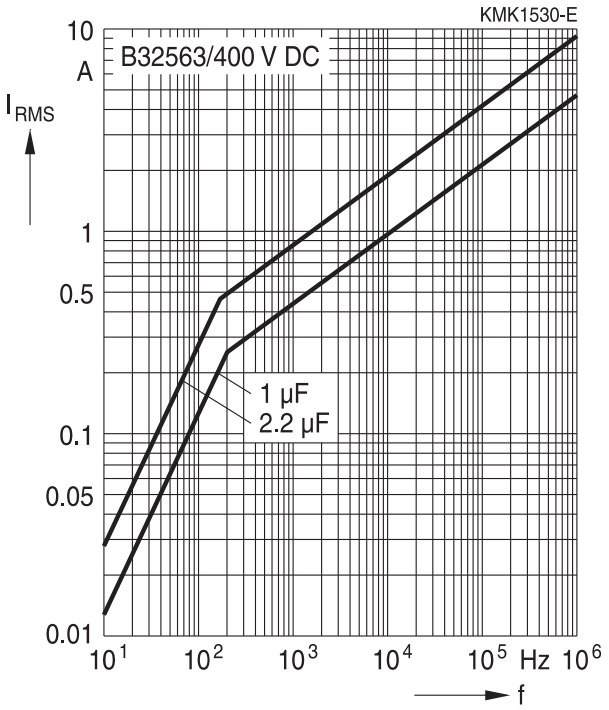
100 V DC/63 V AC



250 V DC/160 V AC



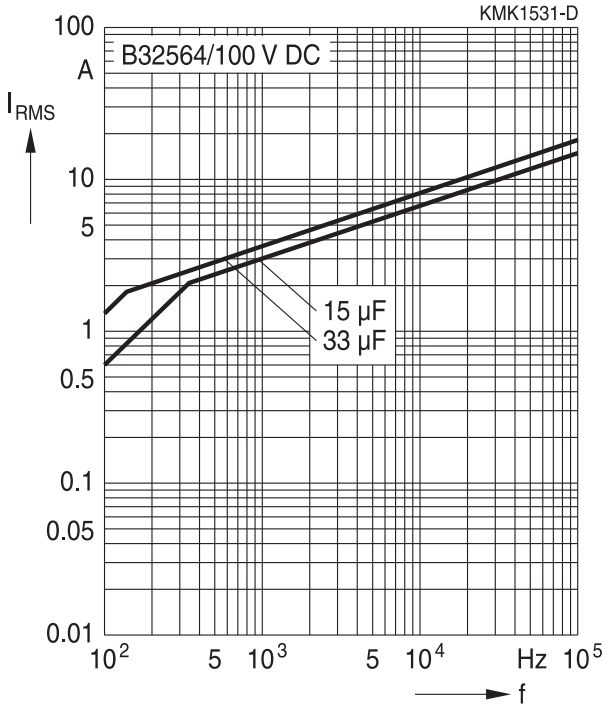
400 V DC/200 V AC



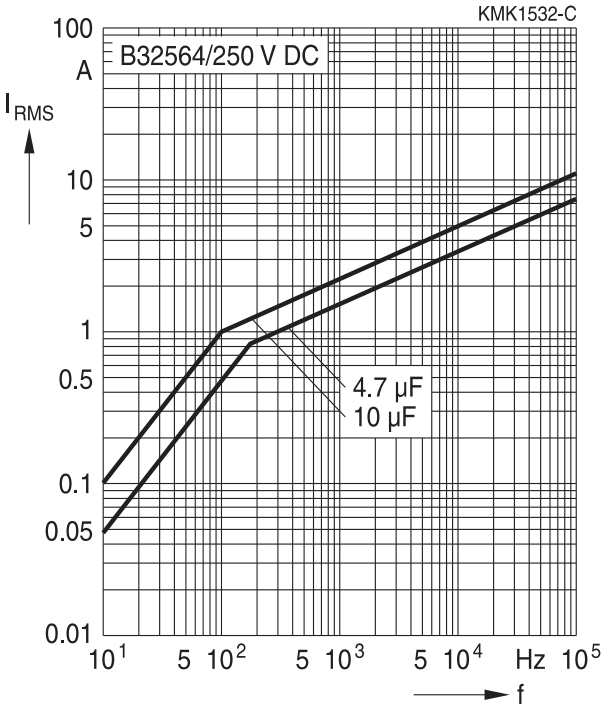
Permissible current I_{RMS} versus frequency f (for sinusoidal waveforms, $T_A \leq 55$ °C)

Lead spacing 27.5 mm

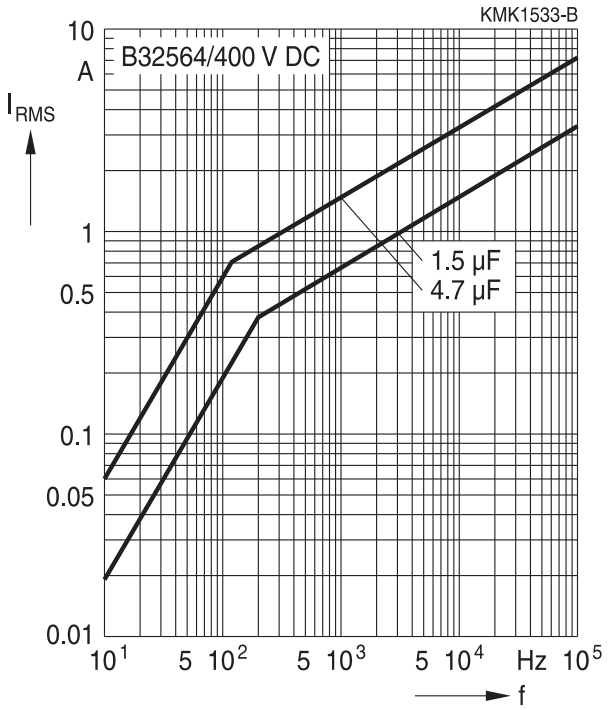
100 V DC/63 V AC



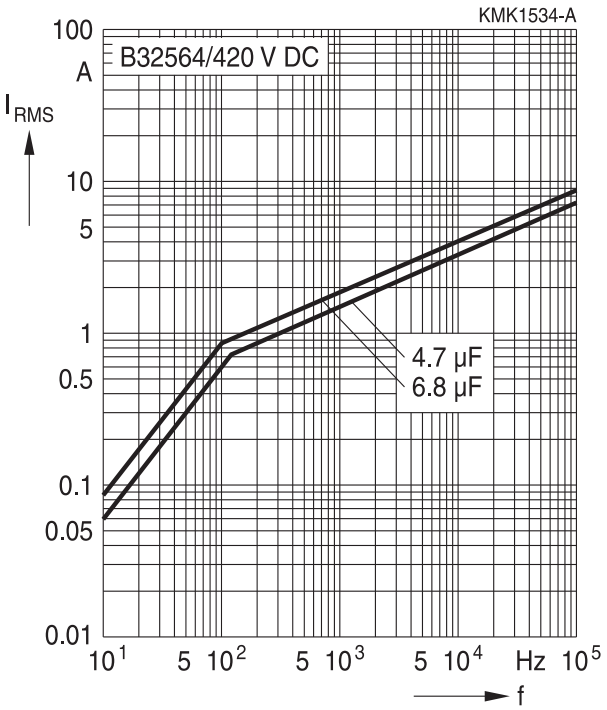
250 V DC/160 V AC



400 V DC/200 V AC



420 V DC/200 V AC



Testing and Standards

Test	Reference	Conditions of test	Performance requirements
Electrical parameters	IEC 60384-2:2005	Voltage proof, 1.4 V_R, 1 minute Insulation resistance, R_{ins} Capacitance, C Dissipation factor, tan δ	Within specified limits
Robustness of terminations	IEC 60068-2-21:2006	Tensile strength (test Ua1) Wire diameter / Tensile force 0.3 <d_1 ≤0.5 mm / 5 N 0.5 <d_1 ≤0.8 mm / 10 N	No visible damage Capacitance and tan δ within specified limits
Resistance to soldering heat	IEC 60068-2-20:2008, test Tb, method 1A	Solder bath temperature at 260 ±5 °C, immersion for 4 seconds (lead spacing ≤10mm) 10 seconds (lead spacing > 10mm)	$\Delta C/C_0$ ≤2% $\lvert\Delta \tan\delta\rvert$ ≤0.003 for C ≤ 1 µF $\lvert\Delta \tan\delta\rvert$ ≤0.002 for C > 1 µF
Rapid change of temperature	IEC 60384-2:2005	T_A = lower category temperature T_B = upper category temperature Five cycles, duration t = 30 min.	$\Delta C/C_0$ ≤5% $\lvert\Delta \tan\delta\rvert$ ≤0.003 for C ≤ 1 µF $\lvert\Delta \tan\delta\rvert$ ≤0.002 for C > 1 µF R_{ins} ≥50% of initial limit
Vibration	IEC 60384-2:2005	Test Fc: vibration sinusoidal Displacement: 0.75 mm Accleration: 98 m/s² Frequency: 10 Hz ... 500 Hz Test duration: 3 orthogonal axes, 2 hours each axe	No visible damage
Bump	IEC 60384-2:2005	Test Eb: Total 4000 bumps with 390 m/s² mounted on PCB Duration: 6 ms	$\Delta C/C_0$ ≤5% $\lvert\Delta \tan\delta\rvert$ ≤0.003 for C ≤1 µF $\lvert\Delta \tan\delta\rvert$ ≤0.002 for C > 1 µF R_{ins} ≥50% of initial limit
Climatic sequence	IEC 60384-2:2005	Dry heat Tb / 16 h Damp heat cyclic, 1st cycle +55 °C / 24 h / 95% ... 100% RH Cold Ta / 2 h Damp heat cyclic, 5 cycles +55 °C / 24 h / 95% ... 100% RH	$\Delta C/C_0$ ≤5% $\lvert\Delta \tan\delta\rvert$ ≤ 0.005 for C ≤ 1 µF $\lvert\Delta \tan\delta\rvert$ ≤ 0.003 for C > 1 µF R_{ins} ≥50% of initial limit
Damp heat, steady state	IEC 60384-2:2005	Test Ca 40 °C / 93% RH / 56 days	No visible damage $\lvert\Delta C/C_0\rvert$ ≤5% $\lvert\Delta \tan\delta\rvert$ ≤ 0.005 R_{ins} ≥50% of initial limit

Test	Reference	Conditions of test	Performance requirements
Endurance A	IEC 60384-2:2005	85 °C / 1.25 V_R / 2000 hours	No visible damage $\|\Delta C/C_0\| \leq 5\%$ $\|\Delta \tan\delta\| \leq 0.003$ for $C \leq 1$ µF $\|\Delta \tan\delta\| \leq 0.002$ for $C > 1$ µF R_{ins} ≥50% of initial limit
Endurance B	IEC 60384-2:2005	125 °C / 1.25 V_C / 2000 hours	No visible damage $\|\Delta C/C_0\| \leq 5\%$ $\|\Delta \tan\delta\| \leq 0.003$ for $C \leq 1$ µF $\|\Delta \tan\delta\| \leq 0.002$ for $C > 1$ µF R_{ins} ≥50% of initial limit

Mounting guidelines

1 Soldering

1.1 Solderability of leads

The solderability of terminal leads is tested to IEC 60068-2-20, test Ta, method 1.

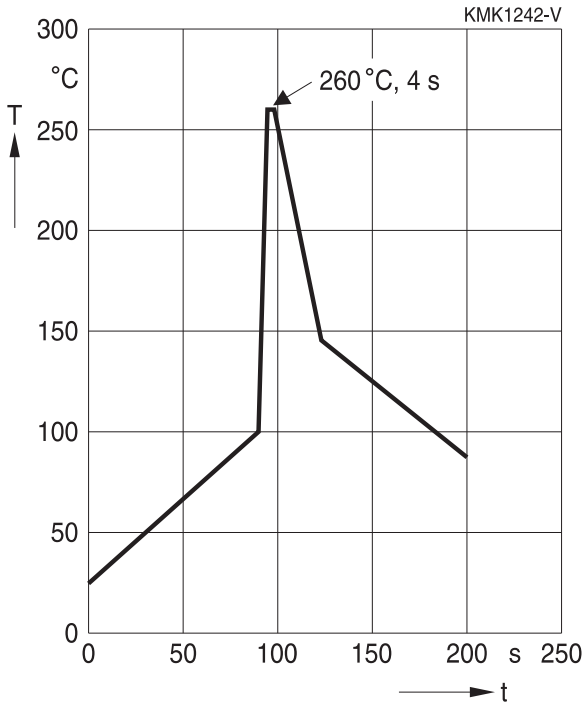
Before a solderability test is carried out, terminals are subjected to accelerated ageing (to IEC 60068-2-2, test Ba: 4 h exposure to dry heat at 155 °C). Since the ageing temperature is far higher than the upper category temperature of the capacitors, the terminal wires should be cut off from the capacitor before the ageing procedure to prevent the solderability being impaired by the products of any capacitor decomposition that might occur.

Solder bath temperature	235 ±5 °C
Soldering time	2.0 ±0.5 s
Immersion depth	2.0 +0/−0.5 mm from capacitor body or seating plane
Evaluation criteria: Visual inspection	Wetting of wire surface by new solder ≥90%, free-flowing solder

1.2 Resistance to soldering heat

Resistance to soldering heat is tested to IEC 60068-2-20, test Tb, method 1.
Conditions:

Series		Solder bath temperature	Soldering time
MKT	boxed (except 2.5 × 6.5 × 7.2 mm) coated uncoated (lead spacing >10 mm)	260 ±5 °C	10 ±1 s
MFP MKP	(lead spacing >7.5 mm)		
MKT	boxed (case 2.5 × 6.5 × 7.2 mm)		5 ±1 s
MKP MKT	(lead spacing ≤7.5 mm) uncoated (lead spacing ≤10 mm) insulated (B32559)		<4 s recommended soldering profile for MKT uncoated (lead spacing ≤ 10 mm) and insulated (B32559)



Immersion depth	2.0 +0/−0.5 mm from capacitor body or seating plane
Shield	Heat-absorbing board, (1.5 ±0.5) mm thick, between capacitor body and liquid solder
Evaluation criteria:	
Visual inspection	No visible damage
$\Delta C/C_0$	2% for MKT/MKP/MFP 5% for EMI suppression capacitors
tan δ	As specified in sectional specification

1.3 General notes on soldering

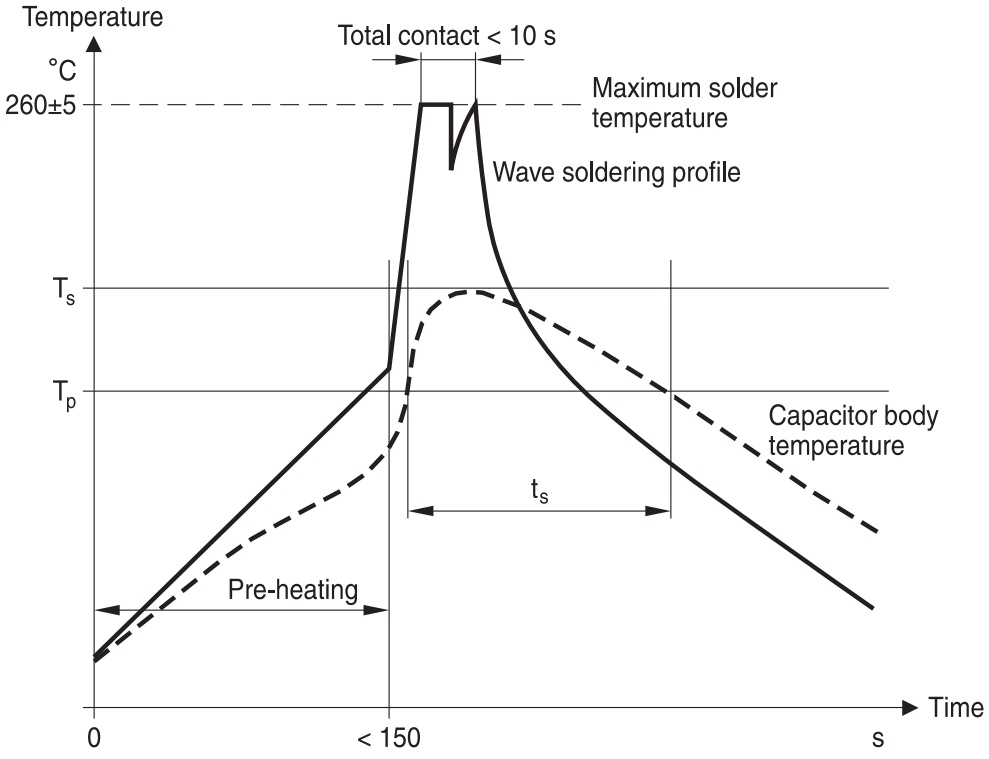
Permissible heat exposure loads on film capacitors are primarily characterized by the upper category temperature T_{max}. Long exposure to temperatures above this type-related temperature limit can lead to changes in the plastic dielectric and thus change irreversibly a capacitor's electrical characteristics. For short exposures (as in practical soldering processes) the heat load (and thus the possible effects on a capacitor) will also depend on other factors like:

- Pre-heating temperature and time
- Forced cooling immediately after soldering
- Terminal characteristics:
  diameter, length, thermal resistance, special configurations (e.g. crimping)
- Height of capacitor above solder bath
- Shadowing by neighboring components
- Additional heating due to heat dissipation by neighboring components
- Use of solder-resist coatings

The overheating associated with some of these factors can usually be reduced by suitable countermeasures. For example, if a pre-heating step cannot be avoided, an additional or reinforced cooling process may possibly have to be included.

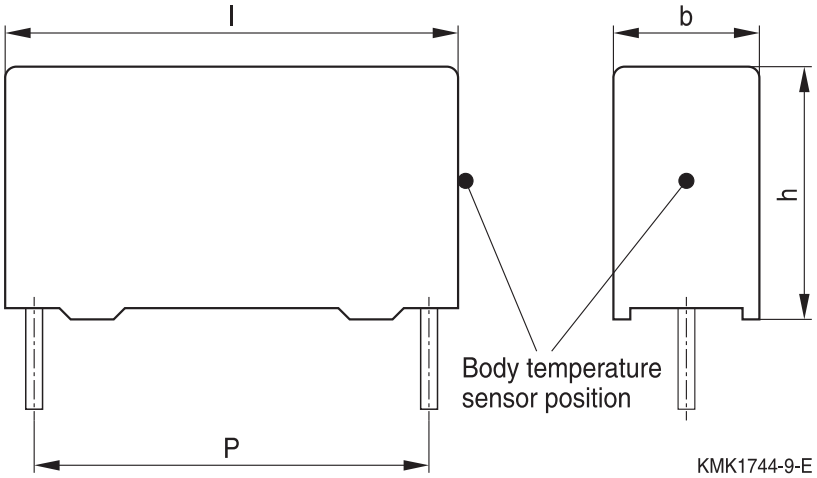
Recommendations

As a reference, the recommended wave soldering profile for our film capacitors is as follows:



T_s: Capacitor body maximum temperature at wave soldering
T_p: Capacitor body maximum temperature at pre-heating

KMK1745-A-E



Body temperature should follow the description below:

- MKT capacitor
  During pre-heating: $T_p \leq 125$ °C
  During soldering: $T_s \leq 160$ °C, $t_s \leq 45$ s

When SMD components are used together with leaded ones, the film capacitors should not pass into the SMD adhesive curing oven. The leaded components should be assembled after the SMD curing step.

Leaded film capacitors are not suitable for reflow soldering.

In order to ensure proper conditions for manual or selective soldering, the body temperature of the capacitor (T_s) must be ≤120 °C.

One recommended condition for manual soldering is that the tip of the soldering iron should be <360 °C and the soldering contact time should be no longer than 3 seconds.

For uncoated MKT capacitors with lead spacings ≤10 mm (B32560/B32561) the following measures are recommended:

- pre-heating to not more than 110 °C in the preheater phase
- rapid cooling after soldering

Please refer to our Film Capacitors Data Book in case more details are needed.

Cautions and warnings

- Do not exceed the upper category temperature (UCT).
- Do not apply any mechanical stress to the capacitor terminals.
- Avoid any compressive, tensile or flexural stress.
- Do not move the capacitor after it has been soldered to the PC board.
- Do not pick up the PC board by the soldered capacitor.
- Do not place the capacitor on a PC board whose PTH hole spacing differs from the specified lead spacing.
- Do not exceed the specified time or temperature limits during soldering.
- Avoid external energy inputs, such as fire or electricity.
- Avoid overload of the capacitors.
- Consult us if application is with severe temperature and humidity condition.
- There are no serviceable or repairable parts inside the capacitor. Opening the capacitor or any attempts to open or repair the capacitor will void the warranty and liability of TDK Electronics.
- Please note that the standards referred to in this publication may have been revised in the meantime.

The table below summarizes the safety instructions that must always be observed. A detailed description can be found in the relevant sections of the chapters "General technical information" and "Mounting guidelines".

Topic	Safety information	Reference chapter "General technical information"
Storage conditions	Make sure that capacitors are stored within the specified range of time, temperature and humidity conditions.	4.5 "Storage conditions"
Flammability	Avoid external energy, such as fire or electricity (passive flammability), avoid overload of the capacitors (active flammability) and consider the flammability of materials.	5.3 "Flammability"
Resistance to vibration	Do not exceed the tested ability to withstand vibration. The capacitors are tested to IEC 60068-2-6:2007. TDK Electronics offers film capacitors specially designed for operation under more severe vibration regimes such as those found in automotive applications. Consult our catalog "Film Capacitors for Automotive Electronics".	5.2 "Resistance to vibration"

Topic	Safety information	Reference chapter "Mounting guidelines"
Soldering	Do not exceed the specified time or temperature limits during soldering.	1 "Soldering"
Cleaning	Use only suitable solvents for cleaning capacitors.	2 "Cleaning"
Embedding of capacitors in finished assemblies	When embedding finished circuit assemblies in plastic resins, chemical and thermal influences must be taken into account. Caution: Consult us first, if you also wish to embed other uncoated component types!	3 "Embedding of capacitors in finished assemblies"

Display of ordering codes for TDK Electronics products

The ordering code for one and the same product can be represented differently in data sheets, data books, other publications, on the company website, or in order-related documents such as shipping notes, order confirmations and product labels. The varying representations of the ordering codes are due to different processes employed and do not affect the specifications of the respective products.
Detailed information can be found on the Internet under
www.tdk-electronics.tdk.com/orderingcodes.

Correlation of data sheet values and modelling tool outputs

Data sheet values and results of design tools may deviate as they have not been derived in the same context.
While data sheets show individual parameter statements without considering a possible dependency to other parameters. Tools model a complete given scenario as input and processed inside the tool.
Furthermore as we constantly strive to improve our models, the results of tools can change over time and be a non-binding indication only.

Symbols and terms

Symbol	English	German
α	Heat transfer coefficient	Wärmeübergangszahl
α_C	Temperature coefficient of capacitance	Temperaturkoeffizient der Kapazität
A	Capacitor surface area	Kondensatoroberfläche
β_C	Humidity coefficient of capacitance	Feuchtekoeffizient der Kapazität
C	Capacitance	Kapazität
C_R	Rated capacitance	Nennkapazität
ΔC	Absolute capacitance change	Absolute Kapazitätsänderung
$\Delta C/C$	Relative capacitance change (relative deviation of actual value)	Relative Kapazitätsänderung (relative Abweichung vom Ist-Wert)
$\Delta C/C_R$	Capacitance tolerance (relative deviation from rated capacitance)	Kapazitätstoleranz (relative Abweichung vom Nennwert)
dt	Time differential	Differentielle Zeit
Δt	Time interval	Zeitintervall
ΔT	Absolute temperature change (self-heating)	Absolute Temperaturänderung (Selbsterwärmung)
$\Delta \tan \delta$	Absolute change of dissipation factor	Absolute Änderung des Verlustfaktors
ΔV	Absolute voltage change	Absolute Spannungsänderung
dV/dt	Time differential of voltage function (rate of voltage rise)	Differentielle Spannungsänderung (Spannungsflankensteilheit)
$\Delta V/\Delta t$	Voltage change per time interval	Spannungsänderung pro Zeitintervall
E	Activation energy for diffusion	Aktivierungsenergie zur Diffusion
ESL	Self-inductance	Eigeninduktivität
ESR	Equivalent series resistance	Ersatz-Serienwiderstand
f	Frequency	Frequenz
f_1	Frequency limit for reducing permissible AC voltage due to thermal limits	Grenzfrequenz für thermisch bedingte Reduzierung der zulässigen Wechselspannung
f_2	Frequency limit for reducing permissible AC voltage due to current limit	Grenzfrequenz für strombedingte Reduzierung der zulässigen Wechselspannung
f_r	Resonant frequency	Resonanzfrequenz
F_D	Thermal acceleration factor for diffusion	Therm. Beschleunigungsfaktor zur Diffusion
F_T	Derating factor	Deratingfaktor
i	Current (peak)	Stromspitze
I_C	Category current (max. continuous current)	Kategoriestrom (max. Dauerstrom)

Symbol	English	German
I_{RMS}	(Sinusoidal) alternating current, root-mean-square value	(Sinusförmiger) Wechselstrom
i_z	Capacitance drift	Inkonstanz der Kapazität
k_0	Pulse characteristic	Impulskennwert
L_S	Series inductance	Serieninduktivität
λ	Failure rate	Ausfallrate
λ_0	Constant failure rate during useful service life	Konstante Ausfallrate in der Nutzungsphase
λ_{test}	Failure rate, determined by tests	Experimentell ermittelte Ausfallrate
P_{diss}	Dissipated power	Abgegebene Verlustleistung
P_{gen}	Generated power	Erzeugte Verlustleistung
Q	Heat energy	Wärmeenergie
ρ	Density of water vapor in air	Dichte von Wasserdampf in Luft
R	Universal molar constant for gases	Allg. Molarkonstante für Gas
R	Ohmic resistance of discharge circuit	Ohmscher Widerstand des Entladekreises
R_i	Internal resistance	Innenwiderstand
R_{ins}	Insulation resistance	Isolationswiderstand
R_P	Parallel resistance	Parallelwiderstand
R_S	Series resistance	Serienwiderstand
S	severity (humidity test)	Schärfegrad (Feuchtetest)
t	Time	Zeit
T	Temperature	Temperatur
τ	Time constant	Zeitkonstante
tan δ	Dissipation factor	Verlustfaktor
tan δ_D	Dielectric component of dissipation factor	Dielektrischer Anteil des Verlustfaktors
tan δ_P	Parallel component of dissipation factor	Parallelanteil des Verlfustfaktors
tan δ_S	Series component of dissipation factor	Serienanteil des Verlustfaktors
T_A	Temperature of the air surrounding the component	Temperatur der Luft, die das Bauteil umgibt
T_{max}	Upper category temperature	Obere Kategorietemperatur
T_{min}	Lower category temperature	Untere Kategorietemperatur
t_{OL}	Operating life at operating temperature and voltage	Betriebszeit bei Betriebstemperatur und -spannung
T_{op}	Operating temperature, $T_A + \Delta T$	Beriebstemperatur, $T_A + \Delta T$
T_R	Rated temperature	Nenntemperatur
T_{ref}	Reference temperature	Referenztemperatur
t_{SL}	Reference service life	Referenz-Lebensdauer

Symbol	English	German
V_{AC}	AC voltage	Wechselspannung
V_C	Category voltage	Kategoriespannung
$V_{C,RMS}$	Category AC voltage	(Sinusförmige) Kategorie-Wechselspannung
V_{CD}	Corona-discharge onset voltage	Teilentlade-Einsatzspannung
V_{ch}	Charging voltage	Ladespannung
V_{DC}	DC voltage	Gleichspannung
V_{FB}	Fly-back capacitor voltage	Spannung (Flyback)
V_i	Input voltage	Eingangsspannung
V_o	Output voltage	Ausgangsspannung
V_{op}	Operating voltage	Betriebsspannung
V_p	Peak pulse voltage	Impuls-Spitzenspannung
V_{pp}	Peak-to-peak voltage Impedance	Spannungshub
V_R	Rated voltage	Nennspannung
$\hat{v}_R$	Amplitude of rated AC voltage	Amplitude der Nenn-Wechselspannung
V_{RMS}	(Sinusoidal) alternating voltage, root-mean-square value	(Sinusförmige) Wechselspannung
V_{SC}	S-correction voltage	Spannung bei Anwendung "S-correction"
V_{sn}	Snubber capacitor voltage	Spannung bei Anwendung "Beschaltung"
Z	Impedance	Scheinwiderstand
e	Lead spacing	Rastermaß

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